



Product Change Notification / LIAL-12WRCV778

Date:

19-Jan-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 2927.001 and CCB 3280.002 Final Notice: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

Affected CPNs:

[LIAL-12WRCV778_Affected_CPN_01192021.pdf](#)

[LIAL-12WRCV778_Affected_CPN_01192021.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

Pre Change:

Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700A mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock. **or** Assembled at ASSH assembly site using palladium coated copper (PdCu) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900G die attach and G700LY molding compound or CEL-9240HF10AK mold compound material with NiPdAu or Matte tin lead plating in 93 x 93 mils paddle size without lead lock. **and** Tested at ASSH or ANAP Final Test site.

Post Change:Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700A mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock.**or**Assembled at ASSH assembly site using palladium coated copper (PdCu) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900G die attach and G700LY molding compound or CEL-9240HF10AK mold compound material withNiPdAu or Matte tin lead plating in 93 x 93 mils paddle size without lead lock.**or**Assembled at MTAI assembly site using gold (Au) bond wire, 8390A die attach and G600V mold compound material with Matte tin lead plating in 90 x 90 mils paddle size with lead lock.**and**Tested at ASSH, ANAP or MTAI Final Test site.

Pre and Post Change Summary:

	Pre Change			Post Change			
Assembly Site	Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)		Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)		Microchip Technology Thailand (HQ) (MTAI)
Wire material	PdCu	PdCu	CuPdAu	PdCu	PdCu	CuPdAu	Au
Die attach material	8290	EN-4900G		8290	EN-4900G		8390A
Molding compound material	G700A	G700LY	CEL-9240HF 10AK	G700A	G700LY	CEL-9240HF 10AK	G600V
Lead frame material	CDA194	CDA194		CDA194	CDA194		CDA194
Paddle size	60 x 60 mils	93 x 93 mils		60 x 60 mils	93 x 93 mils		90 x 90 mils
Lead Lock	No	No		No	No		Yes
Lead Plating	NiPdAu	NiPdAu	Matte tin	NiPdAu	NiPdAu	Matte tin	Matte Tin

		Pre Change		Post Change		
Final Test Site		ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	Microchip Technology Thailand (MTAI)
Base Quantity Multiple (BQM)	Tube	100	100	100	100	100
	Tape and Reel	4000	4000	4000	4000	4000
Pin1 Orientation	Tube	Pin 1 side (Black)	Not Applicable	Pin 1 side (Black)	Not Applicable	Pin 1 side (White)
	Tape and Reel	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1

Tube	Minor dimensional changes – see attachment
Carrier Tape	No change
Cover Tape	Minor dimensional changes – see attachment
Plastic Reel	Minor dimensional changes – see attachment
Packing Procedure for Tube and Tape & Reel	See attachment

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying MTAL as an additional assembly and final test site

Change Implementation Status:In Progress

Estimated First Ship Date:February 15, 2021 (date code: 2108)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2021					February 2021				
Workweek	01	02	03	04	05	06	07	08	09	10
Qual Report Availability				X						
Final PCN Issue Date				X						
Estimated First Ship Date								X		

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.PCN_LIAL-12WRCV778 Qual_Report – Assembly site Qualification ReportPCN_LIAL-12WRCV778_Qual_Report – Final Test site Qualification Report

Revision History:**January 19, 2021:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-12WRCV778_Pre and Post Change Summary.pdf](#)

[PCN_LIAL-12WRCV778_ Qual Report - Assembly.pdf](#)

[PCN_LIAL-12WRCV778_ Qual Report - Final Test.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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